

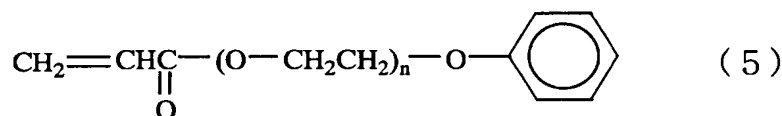
IN THE CLAIMS

Please amend the claims as follows:

Claims 1 to 4. (Canceled)

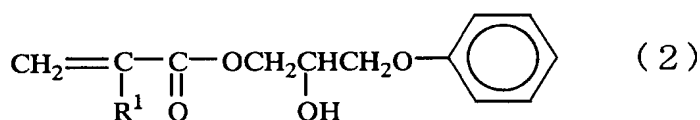
Claim 5. (New): A liquid curing resin composition, comprising the following components (A) and (D):

- (A) 30 to 70 wt % of a urethane (meth)acrylate prepared by reacting polypropylene glycol, polyisocyanate and a hydroxyl-containing (meth)acrylate and having a number-average molecular weight of from 10000 to 40000,
- (B) 40 to 60 wt % of an ethylenically unsaturated monomer having a glass transition point, in the form of a homopolymer, of 60° C or greater,
- (C) 0.1 to 5 wt % of γ -mercaptopropyltrimethoxysilane, and
- (D) a monofunctional polymerizable monomer with the proviso that a monofunctional monomer of formula (5):



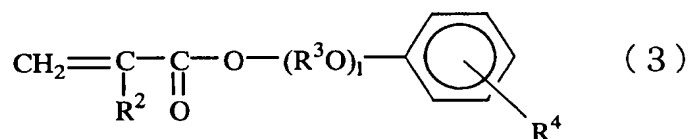
wherein n is an integer ranging from 1 to 5, is excluded from the scope of the claims.

Claim 6 (New). The liquid curing resin composition according to Claim 5, wherein said polyisocyanate is a member selected from the group consisting of 2,4-tolylene diisocyanate, 2,6-tolylene diisocyanate, 1,3-xylylene diisocyanate, 1,4-xylylene diisocyanate, 1,5-naphthalene diisocyanate, m-phenylene diisocyanate, p-phenylene diisocyanate, 3,3'-dimethyl-4,4'-diphenylmethane diisocyanate, 4,4'-diphenylmethane diisocyanate, 3,3'-dimethylphenylene diisocyanate, 4,4'-biphenylene diisocyanate, 1,6-hexane diisocyanate,

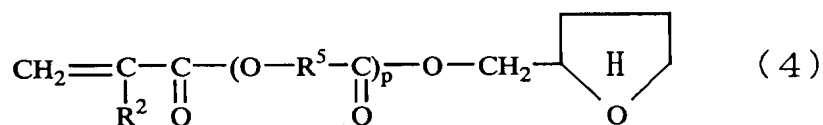
$$\text{CH}_2=\underset{\text{R}^1}{\underset{|}{\text{C}}}-\underset{\text{O}}{\underset{||}{\text{C}}}-\text{OCH}_2\text{CH}_2-(\underset{\text{O}}{\underset{||}{\text{C}}}\text{CH}_2\text{CH}_2\text{CH}_2\text{CH}_2\text{CH}_2)_m-\text{OH} \quad (1)$$


Claim 8 (New): The liquid curing resin composition according to Claim 5, wherein the monofunctional polymerizable monomer is benzyl (meth)acrylate, nonyl (meth)acrylate, dodecyl (meth)acrylate, lauryl (meth)acrylate, isobutyl (meth)acrylate, 2-ethylhexyl

(meth)acrylate, 2-ethylhexylcarbitol (meth)acrylate, 2-hydroxyethyl (meth)acrylate, 2-hydroxypropyl (meth)acrylate, 2-hydroxybutyl (meth)acrylate, polyethylene glycol (meth)acrylate, polypropylene glycol (meth)acrylate, methoxypolyethylene glycol (meth)acrylate, methoxypolypropylene glycol (meth)acrylate, tetrahydrofurfuryl (meth)acrylate, 2-acryloyloxyethyl succinic acid, propyl (meth)acrylate, isopropyl (meth)acrylate, butyl (meth)acrylate, amyl (meth)acrylate, t-butyl (meth)acrylate, pentyl (meth)acrylate, isoamyl (meth)acrylate, hexyl (meth)acrylate, heptyl (meth)acrylate, octyl (meth)acrylate, isooctyl (meth)acrylate, isodecyl (meth)acrylate, undecyl (meth)acrylate, octadecyl (meth)acrylate, stearyl (meth)acrylate, butoxyethyl (meth)acrylate, ethoxydiethylene glycol (meth)acrylate, cyclohexyl acrylate, ethoxyethyl (meth)acrylate, methoxypolyethylene glycol (meth)acrylate, methoxypolypropylene glycol (meth)acrylate, bornyl (meth)acrylate, t-octyl (meth)acrylamide, dimethylaminoethyl (meth)acrylate, diethylaminoethyl (meth)acrylate, 7-amino-3,7-dimethyloctyl (meth)acrylate, and (meth)acrylate compounds represented by the following formula (3) or (4):



wherein, R^2 represents a hydrogen atom or a methyl group, R^3 represents an alkylene group having 2 to 6 carbon atoms, R^4 represents an alkyl group having 1 to 12 carbon atoms, and l is 0 to 12,



wherein, R^2 has the same meaning as described above, R^5 represents an alkylene group having 2 to 8 carbon atoms, and p is 1 to 8.

Claim 9 (New). The liquid curing resin composition according to Claim 5, wherein component (B) comprises at least one compound selected from the group consisting of acryloylmorpholine, dimethylacrylamide, N-vinylpyrrolidone and N-vinylcaprolactam.

Claim 10. (New) A method of adhesively bonding PET films, comprising:
laminating the PET films by applying the liquid curing resin composition according to Claim 5 or 9 therebetween, and
curing the composition by exposure to radiation.

Claim 11. (New) The method of Claim 10, wherein said radiation is UV radiation.

Claim 12. (New) A method of adhesively bonding a MS plate and a PET film,
comprising:
laminating the PET film to the MS plate by applying the liquid curing resin
composition according to Claim 5 or 9 therebetween, and
curing the composition by exposure to radiation.

Claim 13. (New) The method of Claim 12, wherein said radiation is UV radiation.